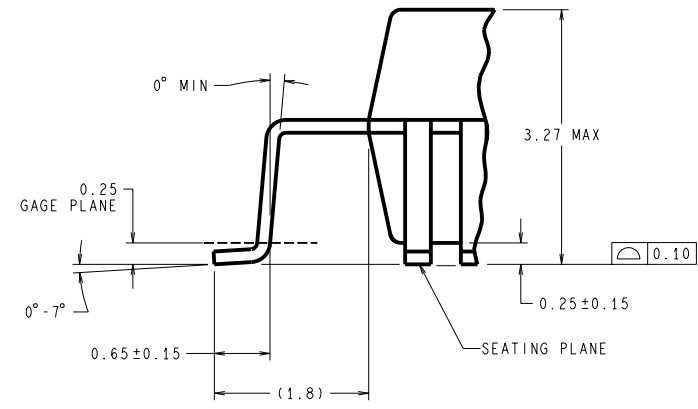
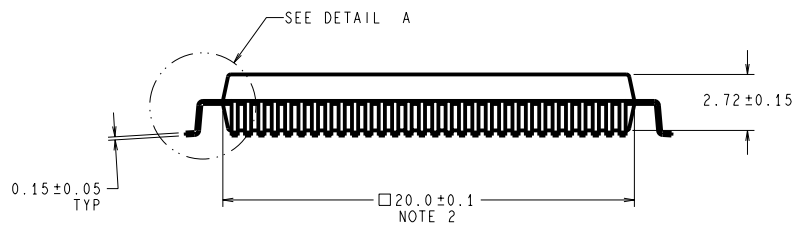
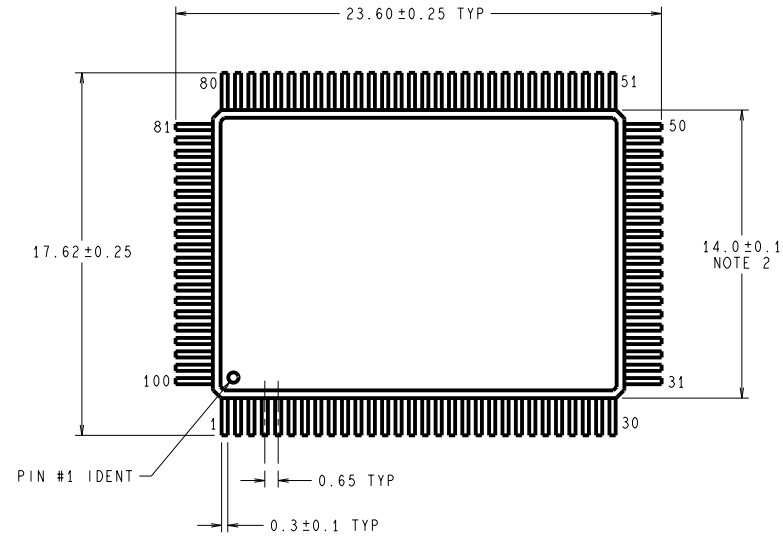


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	10943	05/10/95	MS/



DETAIL A
TYP, SCALE: 25X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE ASE, 100 LD QFP PACKAGE OUTLINE,
DRAWING No. 64-06-A000-3470.

APPROVALS		DATE	National Semiconductor		
DRAWN <i>MARTA SUCHY</i>		05/10/95	2900 Semiconductor dr., Santa Clara, CA 95052-8090		
DFTG. CHK.			POFP, (S), 14 X 20 X 2.7mm, 100 LEAD		
ENGR. CHK.					
PROJECTION INCH [MM]		SCALE N/A	SIZE C	DRAWING NUMBER MKT-VCG100A	REV A
DO NOT SCALE DRAWING SHEET 1 of 1					